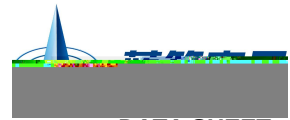


		! " #	\$! % & '	! () % * +	, -	. /
				0 1 2 3 4 5 6 7 8	9 : ;	< = >
				? @ 4 4 A 0 1) B C 3 4 D E 7 8 F G H I J K L M N O P Q R S T U D E B C % V W Q R X Y Z [\ A] ^ _ ` A a b c d \ e f \ g ] ^ _ ` A a b c d \ h	i j	< = >

BRBC847Q

Rev.A Feb.-2022



DATA SHEET

SOT-23

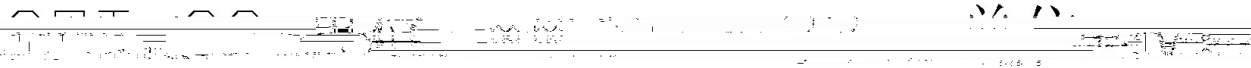
NPN

Silicon NPN transistor in a SOT-23

Parameter

Symbol

/ Package Dimensions



Symbol		Dimensions in Millimeters		Symbol		Dimensions in Millimeters	
A	Max	0.10	0.10	B	Max	2.90	3.40
	Min				Min		
M	Max	0.20	0.20	P	Max	0.85	1.05
	Min				Min		
P	Max	7°	7°	Q	Max	0.35	0.35
	Min				Min		

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | | | |
|---|-------|-----|-----------|---------|--|
| 1 | 150 | 200 | 60 | 120sec; | 1.Preheating:150~200°C, Time:60~120sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box	Units/Outer Box			
SOT-23	2,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205